



3.3V/2.5V LVCMOS 1:12 Clock Fanout Buffer

Features

- 12 LVCMOS compatible clock outputs
- Selectable LVCMOS and differential LVPECL compatible clock inputs
- Maximum clock frequency of 350MHz
- Maximum clock skew of 150pS
- Synchronous output stop in logic low state eliminates output runt pulses
- High-impedance output control
- 3.3V or 2.5V power supply
- Drives up to 24 series terminated clock lines
- Ambient temperature range -40°C to $+85^{\circ}\text{C}$
- 32-Lead LQFP & TQFP packaging
- Supports clock distribution in networking, telecommunication and computing applications
- Pin and Function compatible to MPC9448 and MPC948

Functional Description

The ASM2I99448 is a 3.3V or 2.5V compatible, 1:12 clock fanout buffer targeted for high performance clock tree applications. With output frequencies up to 350 MHz and output skews less than 150 pS, the device meets the needs of most demanding clock applications.

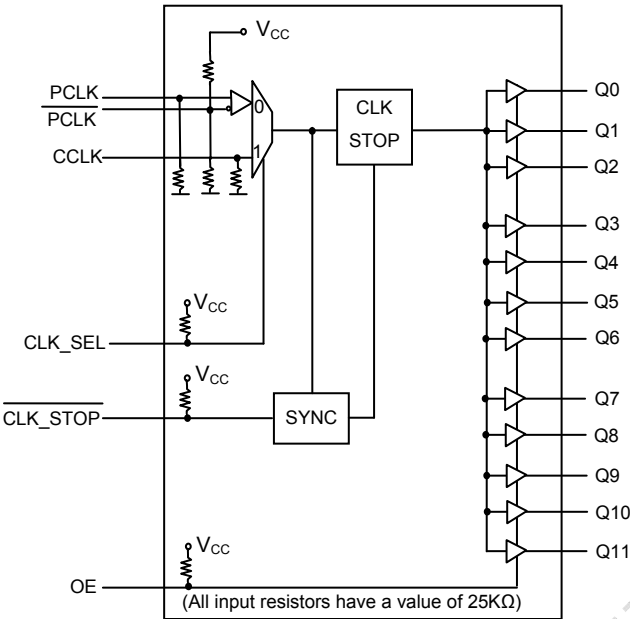
The ASM2I99448 is specifically designed to distribute LVCMOS compatible clock signals up to a frequency of 350MHz. Each output provides a precise copy of the input signal with a near zero skew. The outputs buffers support driving of 50 Ω terminated transmission lines on the incident edge: each output is capable of driving either one parallel terminated or two series terminated transmission lines.

Two selectable, independent clock inputs are available, providing support of LVCMOS and differential LVPECL clock distribution systems. The ASM2I99448 $\overline{\text{CLK_STOP}}$ control is synchronous to the falling edge of the input clock. It allows the start and stop of the output clock signal only in a logic low state, thus eliminating potential output runt pulses. Applying the OE control will force the outputs into high-impedance mode.

All inputs have an internal pull-up or pull-down resistor preventing unused and open inputs from floating. The device supports a 2.5V or 3.3V power supply and an ambient temperature range of -40°C to $+85^{\circ}\text{C}$. The ASM2I99448 is pin and function compatible but performance-enhanced to the MPC948.



Block Diagram



Pin Diagram

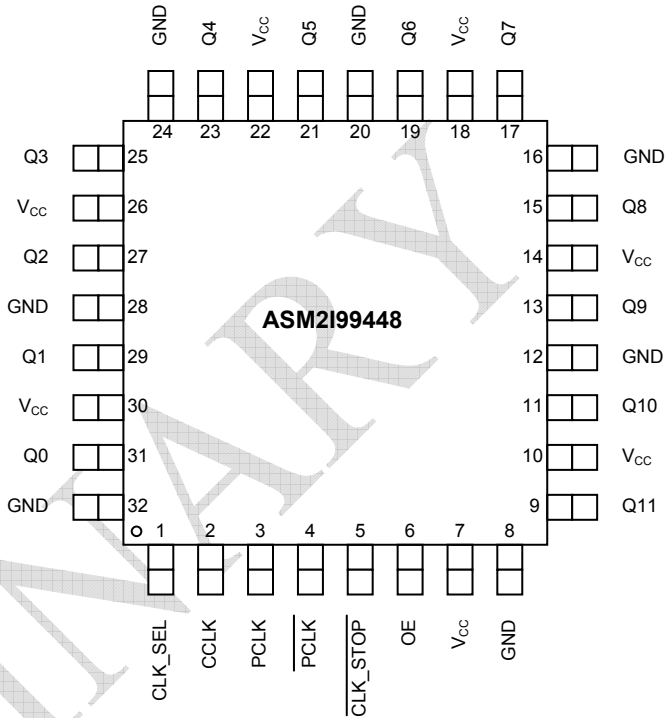


Table 1. FUNCTION TABLE

Control	Default	0	1
CLK_SEL	1	PECL differential input selected	CCLK input selected
OE	1	Outputs disabled (high-impedance state) ¹	Outputs enabled
$\overline{\text{CLK_STOP}}$	1	Outputs synchronously stopped in logic low state	Outputs active

Note: 1. OE=0 will high-impedance tristate all outputs independent on $\overline{\text{CLK_STOP}}$.



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Table 2. PIN CONFIGURATION

Pin#	Pin Name	I/O	Type	Function
4,3	$\overline{\text{PCLK}}$, PCLK	Input	LVPECL	LVPECL Clock Inputs
2	CCLK	Input	LVC MOS	Alternative clock signal input
1	CLK_SEL	Input	LVC MOS	Clock input select
5	$\overline{\text{CLK_STOP}}$	Input	LVC MOS	Clock output enable/disable
6	OE	Input	LVC MOS	Output enable/disable (high-impedance tristate)
31,29,27,25,23,21,19,17,15,13,11,9	Q0 – Q11	Output	LVC MOS	Clock output
8,12,16,20,24,28,32	GND	Supply	Ground	Negative power supply (GND) for I/O and core.
7,10,14,18,22,26,30	V _{CC}	Supply	V _{CC}	Positive power supply for I/O and core. All V _{CC} pins must be connected to the positive power supply for correct operation

Table 3. ABSOLUTE MAXIMUM RATINGS¹

Symbol	Parameter	Min	Max	Unit
V _{CC}	Supply Voltage	–0.3	3.9	V
V _{IN}	DC Input Voltage	–0.3	V _{CC} + 0.3	V
V _{OUT}	DC Output Voltage	–0.3	V _{CC} + 0.3	V
I _{IN}	DC Input Current		±20	mA
I _{OUT}	DC Output Current		±50	mA
T _{Stor}	Storage Temperature Range	–65	125	°C

Note: 1. These are stress ratings only and are not implied for functional use. Exposure to absolute maximum ratings for prolonged periods of time may affect device reliability.



Table 4. GENERAL SPECIFICATIONS

Symbol	Characteristic	Min	Typ	Max	Unit	Condition
V_{TT}	Output Termination Voltage		$V_{CC}+2$		V	
MM	ESD Protection (Machine Model)	200			V	
HBM	ESD Protection (Human Body Model)	2000			V	
LU	Latch-up Immunity	200			mA	
C_{PD}	Power Dissipation Capacitance		10		pF	Per Output
C_{IN}	Input Capacitance		4.0		pF	Inputs

Table 5. DC CHARACTERISTICS ($V_{CC} = 3.3V \pm 5\%$, $T_A = -40^{\circ}C$ to $+85^{\circ}C$)

Symbol	Characteristic		Min	Typ	Max	Unit	Condition
V_{IH}	Input HIGH Voltage		2.0		$V_{CC} + 0.3$	V	LVC MOS
V_{IL}	Input LOW Voltage		-0.3		0.8	V	LVC MOS
V_{PP}	Peak-to-Peak Input Voltage	PCLK	250			mV	LVPECL
V_{CMR}^1	Common Mode Range	PCLK	1.1		$V_{CC} - 0.6$	V	LVPECL
I_{IN}	Input Current ²				300	μA	$V_{IN} = V_{CC}$ or GND
V_{OH}	Output HIGH Voltage		2.4			V	$I_{OH} = -24mA^3$
V_{OL}	Output LOW Voltage				0.55 0.30	V V	$I_{OL} = 24mA^3$ $I_{OL} = 12mA$
Z_{OUT}	Output Impedance			17		Ω	
I_{CCQ}^4	Maximum Quiescent Supply Current				2.0	mA	All V_{CC} Pins

Note: 1. V_{CMR} (DC) is the crosspoint of the differential input signal. Functional operation is obtained when the crosspoint is within the V_{CMR} range and the input swing lies within the V_{PP} (DC) specification.

2. Input pull-up / pull-down resistors influence input current.

3. The ASM2I99448 is capable of driving 50 Ω transmission lines on the incident edge. Each output drives one 50 Ω parallel terminated transmission line to a termination voltage of V_{TT} . Alternatively, the device drives up to two 50 Ω series terminated transmission lines (for $V_{CC}=3.3V$) or one 50 Ω series terminated transmission line (for $V_{CC}=2.5V$).

4. I_{CCQ} is the DC current consumption of the device with all outputs open and the input in its default state or open.



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Table 6. AC CHARACTERISTICS ($V_{CC} = 3.3V \pm 5\%$, $T_A = -40^\circ C$ to $+85^\circ C$)¹

Symbol	Characteristics	Min	Typ	Max	Unit	Condition
f_{ref}	Input Frequency	0		350	MHz	
f_{MAX}	Maximum Output Frequency	0		350	MHz	
V_{PP}	Peak-to-peak input voltage	PCLK	400	1000	mV	LVPECL
V_{CMR}^2	Common Mode Range	PCLK	1.3	$V_{CC}-0.8$	V	LVPECL
$t_{P, REF}$	Reference Input Pulse Width	1.4			nS	
t_r, t_f	CCLK Input Rise/Fall Time			1.0^3	nS	0.8 to 2.0V
$t_{PLH/HL}$ $t_{PLH/HL}$	Propagation delay	PCLK to any Q CCLK to any Q	1.6 1.3	3.6 3.3	nS nS	
$t_{PLZ, HZ}$	Output Disable Time			11	nS	
$t_{PZL, LZ}$	Output Enable Time			11	nS	
t_s	Setup time	CCLK to $\overline{CLK_STOP}$ PCLK to $\overline{CLK_STOP}$	0.0 0.0		nS nS	
t_H	Hold time	CCLK to $\overline{CLK_STOP}$ PCLK to $\overline{CLK_STOP}$	1.0 1.5		nS nS	
$t_{sk(O)}$	Output-to-output Skew			150	pS	
$t_{sk(PP)}$	Device-to-device Skew	PCLK or CCLK to any Q		2.0	nS	
$t_{SK(P)}$	Output pulse skew ⁴	Using CCLK Using PCLK		300 400	pS pS	
DC_Q	Output Duty Cycle	$f_Q < 170$ MHz	45	50	55	% $DC_{REF} = 50\%$
t_r, t_f	Output Rise/Fall Time		0.1	1.0	nS	0.55 to 2.4V

Note: 1. AC characteristics apply for parallel output termination of 50Ω to V_{TT} .

2. V_{CMR} (AC) is the crosspoint of the differential input signal. Normal AC operation is obtained when the crosspoint is within the V_{CMR} range and the input swing lies within the V_{PP} (AC) specification. Violation of V_{CMR} or V_{PP} impacts $t_{PLH/HL}$ and $t_{SK(PP)}$.

3. Violation of the 1.0 nS maximum input rise and fall time limit will affect the device propagation delay, device-to-device skew, reference input pulse width, output duty cycle and maximum frequency specifications.

4. Output pulse skew is the absolute difference of the propagation delay times: $|t_{PLH} - t_{PHL}|$.

Table 7. DC CHARACTERISTICS ($V_{CC} = 2.5V \pm 5\%$, $T_A = -40^\circ C$ to $+85^\circ C$)

Symbol	Characteristics	Min	Typ	Max	Unit	Condition
V_{IH}	Input high voltage	1.7		$V_{CC} + 0.3$	V	LVC MOS
V_{IL}	Input low voltage	-0.3		0.7	V	LVC MOS
V_{PP}	Peak-to-peak input voltage	PCLK	250		mV	LVPECL
V_{CMR}^1	Common Mode Range	PCLK	1.0	$V_{CC}-0.7$	V	LVPECL
I_{IN}	Input current ²			300	μA	$V_{IN}=GND$ or $V_{IN}=V_{CC}$
V_{OH}	Output High Voltage	1.8			V	$I_{OH} = -15$ mA ³
V_{OL}	Output Low Voltage			0.6	V	$I_{OL} = 15$ mA ³
Z_{OUT}	Output impedance		19		Ω	
I_{CCQ}^4	Maximum Quiescent Supply Current			2.0	mA	All V_{CC} Pins

Note: 1. V_{CMR} (DC) is the crosspoint of the differential input signal. Functional operation is obtained when the crosspoint is within the V_{CMR} range and the input swing lies within the V_{PP} (DC) specification.

2. Input pull-up / pull-down resistors influence input current.

3. The ASM2I99448 is capable of driving 50Ω transmission lines on the incident edge. Each output drives one 50Ω parallel terminated transmission line to a termination voltage of V_{TT} . Alternatively, the device drives one 50Ω series terminated transmission lines at $V_{CC}=2.5V$.

4. I_{CCQ} is the DC current consumption of the device with all outputs open and the input in its default state or open.



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Table 8. AC CHARACTERISTICS ($V_{CC} = 2.5V \pm 5\%$, $T_A = -40^\circ C$ to $+85^\circ C$)¹

Symbol	Characteristics		Min	Typ	Max	Unit	Condition
f_{ref}	Input Frequency		0		350	MHz	
f_{MAX}	Maximum Output Frequency		0		350	MHz	
V_{PP}	Peak-to-peak input voltage	PCLK	400		1000	mV	LVPECL
V_{CMR}^2	Common Mode Range	PCLK	1.2		$V_{CC}-0.8$	V	LVPECL
$t_{P, REF}$	Reference Input Pulse Width		1.4			nS	
t_r, t_f	CCLK Input Rise/Fall Time				1.0 ³	nS	0.8 to 2.0V
$t_{PLH/HL}$	Propagation delay	PCLK to any Q	1.5		4.2	nS	
$t_{PLH/HL}$		CCLK to any Q	1.7		4.4	nS	
$t_{PLZ, HZ}$	Output Disable Time				11	nS	
$t_{PZL, LZ}$	Output Enable Time				11	nS	
t_S	Setup time	CCLK to $\overline{CLK_STOP}$	0.0			nS	
		PCLK to $\overline{CLK_STOP}$	0.0			nS	
t_H	Hold time	CCLK to $\overline{CLK_STOP}$	1.0			nS	
		PCLK to $\overline{CLK_STOP}$	1.5			nS	
$t_{sk(O)}$	Output-to-output Skew				150	pS	
$t_{sk(PP)}$	Device-to-device Skew	PCLK or CCLK to any Q			2.7	nS	
$t_{SK(p)}$	Output pulse skew ⁴	Using CCLK			200	pS	
		Using PCLK			300	pS	
DC_Q	Output Duty Cycle	$f_Q < 350$ MHz and using CLK	45	50	55	%	$DC_{REF} = 50\%$
		$f_Q < 200$ MHz and using PCLK	45	50	55	%	
t_r, t_f	Output Rise/Fall Time		0.1		1.0	nS	0.6 to 1.8V

Note: 1. AC characteristics apply for parallel output termination of 50Ω to V_{TT} .

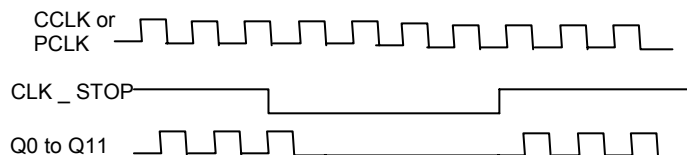
2. V_{CMR} (AC) is the crosspoint of the differential input signal. Normal AC operation is obtained when the crosspoint is within the V_{CMR} range and the input swing lies within the V_{PP} (AC) specification. Violation of V_{CMR} or V_{PP} impacts $t_{PLH/HL}$ and $t_{SK(PP)}$.

3. Violation of the 1.0nS maximum input rise and fall time limit will affect the device propagation delay, device-to-device skew, reference input pulse width, output duty cycle and maximum frequency specifications.

4. Output pulse skew is the absolute difference of the propagation delay times: $|t_{PLH} - t_{PHL}|$.



APPLICATIONS INFORMATION



Timing Diagram
Figure 1. Output Clock Stop (CLK_STOP)

Driving Transmission Lines

The ASM2I99448 clock driver was designed to drive high speed signals in a terminated transmission line environment. To provide the optimum flexibility to the user, the output drivers were designed to exhibit the lowest impedance possible. With an output impedance of 17Ω ($V_{CC}=3.3V$), the outputs can drive either parallel or series terminated transmission lines. In most high performance clock networks, point-to-point distribution of signals is the method of choice. In a point-to-point scheme, either series terminated or parallel terminated transmission lines can be used. The parallel technique terminates the signal at the end of the line with a 50Ω resistance to $V_{CC}\pm 2$.

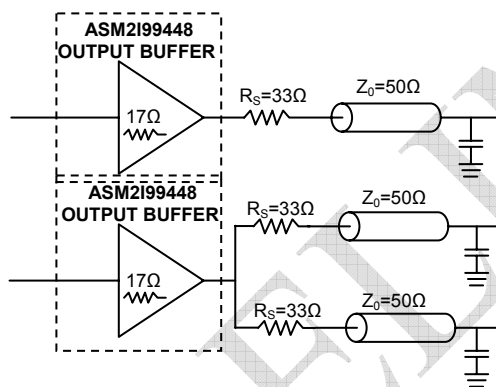


Figure 2. Single versus Dual Transmission Lines

This technique draws a fairly high level of DC current and thus only a single terminated line can be driven by each output of the ASM2I99448 clock driver. For the series terminated case, however, there is no DC current draw; thus, the outputs can drive multiple series terminated lines. Figure 2 “Single versus Dual Transmission Lines” illustrates an output driving a single series terminated line versus two series terminated lines in parallel. When taken to its extreme, the fanout of the ASM2I99448 clock driver is effectively doubled due to its capability to drive multiple lines at $V_{CC}=3.3V$.

The waveform plots in Figure 3 “Single versus Dual Line Termination Waveforms” show the simulation results of an output driving a single line versus two lines. In both

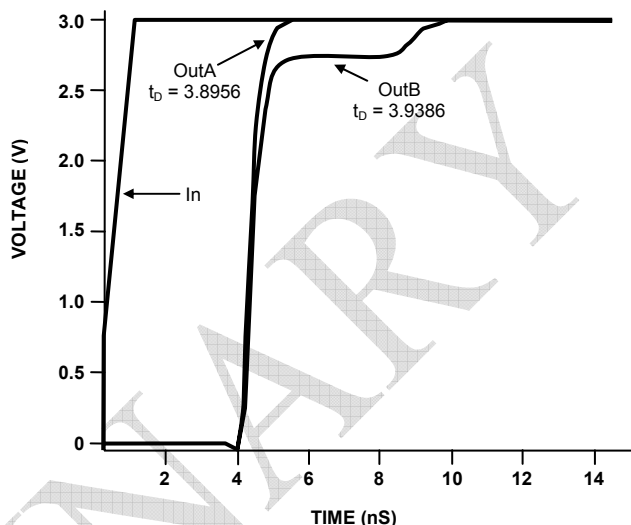


Figure 3 . Single versus Dual Line Termination Waveforms

cases, the drive capability of the ASM2I99448 output buffer is more than sufficient to drive 50Ω transmission lines on the incident edge. Note from the delay measurements in the simulations a delta of only 43pS exists between the two differently loaded outputs. This suggests that the dual line driving need not be used exclusively to maintain the tight output-to-output skew of the ASM2I99448. The output waveform in Figure 3 “Single versus Dual Line Termination Waveforms” shows a step in the waveform; this step is caused by the impedance mismatch seen looking into the driver. The parallel combination of the 33Ω series resistor plus the output impedance does not match the parallel combination of the line impedances. The voltage wave launched down the two lines will equal:

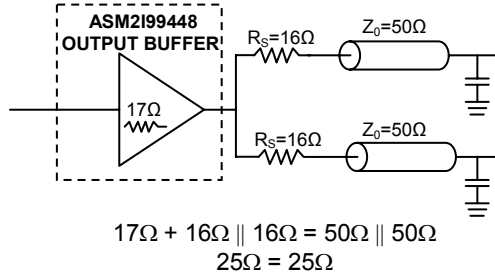
$$\begin{aligned}
 V_L &= V_S (Z_0 \div (R_S + R_0 + Z_0)) \\
 Z_0 &= 50\Omega \parallel 50\Omega \\
 R_S &= 33\Omega \parallel 33\Omega \\
 R_0 &= 17\Omega \\
 V_L &= 3.0 (25 \div (16.5 + 17 + 25)) \\
 &= 1.28V
 \end{aligned}$$

At the load end the voltage will double, due to the near unity reflection coefficient, to 2.5V. It will then increment towards the quiescent 3.0V in steps separated by one round trip delay (in this case 4.0nS).

Since this step is well above the threshold region it will not cause any false clock triggering; however, designers may be uncomfortable with unwanted reflections on the line. To better match the impedances when driving

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multiple lines, the situation in Figure 4 “Optimized Dual Line Termination” should be used. In this case, the series terminating resistors are reduced such that when the parallel combination is added to the output buffer impedance the line impedance is perfectly matched.

**Figure 4. Optimized Dual Line Termination**

Power Consumption of the ASM2199448 and Thermal Management

The ASM2199448 AC specification is guaranteed for the entire operating frequency range up to 350MHz. The ASM2199448 power consumption and the associated long-term reliability may decrease the maximum frequency limit, depending on operating conditions such as clock frequency, supply voltage, output loading, ambient temperature, vertical convection and thermal conductivity of package and board. This section describes the impact of these parameters on the junction temperature and gives a guideline to estimate the ASM2199448 die junction temperature and the associated device reliability.

Table 9. Die junction temperature and MTBF

Junction temperature (°C)	MTBF (Years)
100	20.4
110	9.1
120	4.2
130	2.0

Increased power consumption will increase the die junction temperature and impact the device reliability (MTBF). According to the system-defined tolerable MTBF, the die junction temperature of the ASM2199448 needs to be controlled and the thermal impedance of the board/package should be optimized. The power dissipated in the ASM2199448 is represented in equation 1.

Where ICCQ is the static current consumption of the ASM2199448, CPD is the power dissipation capacitance per output, (M)ΣCL represents the external capacitive output load, N is the number of active outputs (N is always 12 in case of the ASM2199448). The ASM2199448 supports driving transmission lines to maintain high signal integrity and tight timing parameters. Any transmission line will hide the lumped capacitive load at the end of the board trace, therefore, ΣCL is zero for controlled transmission line systems and can be eliminated from equation 1. Using parallel termination output termination results in equation 2 for power dissipation.

In equation 2, P stands for the number of outputs with a parallel or thevenin termination, VOL, IOL, VOH and IOH are a function of the output termination technique and DCQ is the clock signal duty cycle. If transmission lines are used ΣCL is zero in equation 2 and can be eliminated. In general, the use of controlled transmission line techniques eliminates the impact of the lumped capacitive loads at the end lines and greatly reduces the power dissipation of the device. Equation 3 describes the die junction temperature TJ as a function of the power consumption.

Where Rthja is the thermal impedance of the package (junction to ambient) and TA is the ambient temperature. According to Table 9, the junction temperature can be used to estimate the long-term device reliability. Further, combining equation 1 and equation 2 results in a maximum operating frequency for the ASM2199448 in a series terminated transmission line system, equation 4.

$$P_{TOT} = \left[I_{CCQ} + V_{CC} \cdot f_{CLOCK} \cdot \left(N \cdot C_{PD} + \sum_M C_L \right) \right] \cdot V_{CC} \quad \text{Equation 1}$$

$$P_{TOT} = V_{CC} \cdot \left[I_{CCQ} + V_{CC} \cdot f_{CLOCK} \cdot \left(N \cdot C_{PD} + \sum_M C_L \right) \right] + \sum_P \left[DC_Q \cdot I_{OH} (V_{CC} - V_{OH}) + (1 - DC_Q) \cdot I_{OL} \cdot V_{OL} \right] \quad \text{Equation 2}$$

$$T_J = T_A + P_{TOT} \cdot R_{thja} \quad \text{Equation 3}$$

$$f_{CLOCKMAX} = \frac{1}{C_{PD} \cdot N \cdot V_{CC}^2} \cdot \left[\frac{T_{JMAX} - T_A}{R_{thja}} - (I_{CCQ} \cdot V_{CC}) \right] \quad \text{Equation 4}$$



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T_J , MAX should be selected according to the MTBF system requirements and Table 9. R_{thja} can be derived from Table 10. The R_{thja} represent data based on 1S2P boards, using 2S2P boards will result in lower thermal impedance than indicated below.

Table 10. Thermal package impedance of the 32LQFP

Convection, LFPM	R_{thja} (1P2S board), °C/W	R_{thja} (2P2S board), °C/W
Still air	86	61
100 lfpm	76	56
200 lfpm	71	54
300 lfpm	68	53
400 lfpm	66	52
500 lfpm	60	49

If the calculated maximum frequency is below 350 MHz, it becomes the upper clock speed limit for the given application conditions. The following eight derating charts describe the safe frequency operation range for the ASM2I99448. The charts were calculated for a maximum tolerable die junction temperature of 110°C (120°C), corresponding to an estimated MTBF of 9.1 years (4 years), a supply voltage of 3.3V and series terminated transmission line or capacitive loading. Depending on a given set of these operating conditions and the available device convection a decision on the maximum operating frequency can be made.

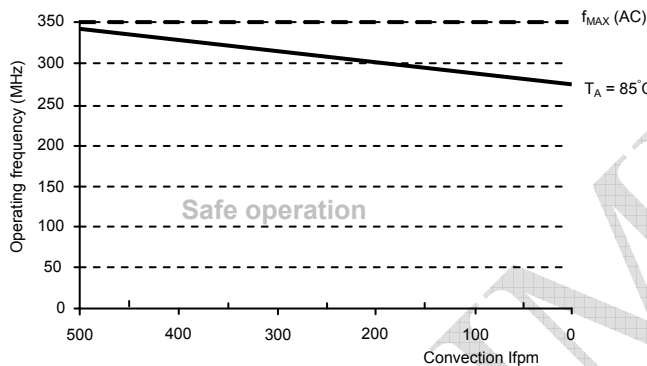


Figure 5. Maximum ASM2I99448 frequency $V_{CC} = 3.3V$, MTBF 9.1 years, driving series terminated transmission lines, 2s2p board

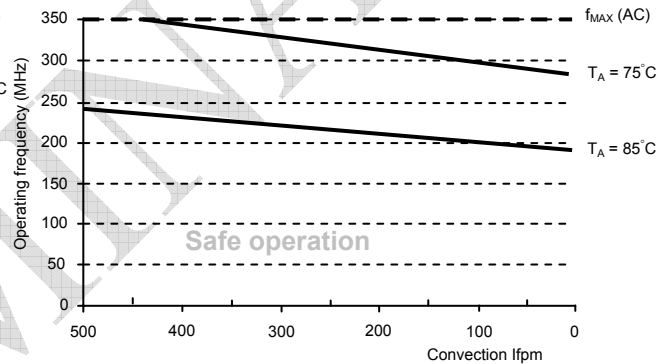


Figure 6. Maximum ASM2I99448 frequency $V_{CC} = 3.3V$, MRBF 9.1 years, 4pF load per line, 2s2p board

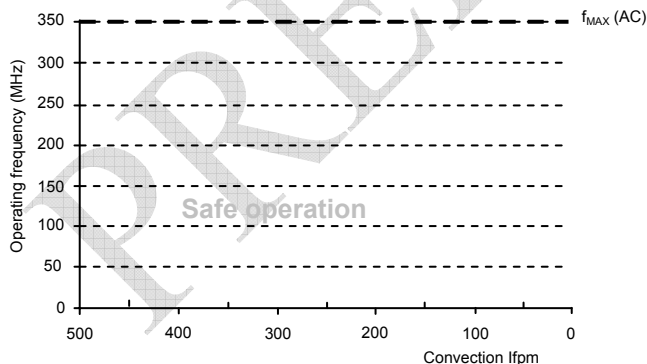


Figure 7. No maximum frequency limitation for $V_{CC} = 3.3V$, MTBF 4 years, driving series terminated transmission lines, 2s2p board

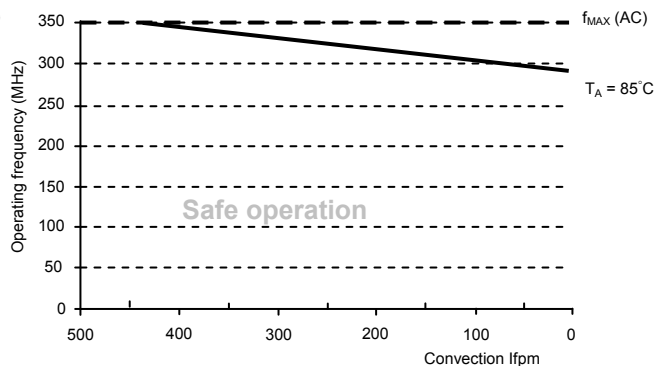


Figure 8. Maximum ASM2I99448 frequency $V_{CC} = 3.3V$, MRBF 4 years, 4pF load per line, 2s2p board



The Following Figures illustrate the Measurement Reference for the ASM2I99448 Clock Driver Circuit

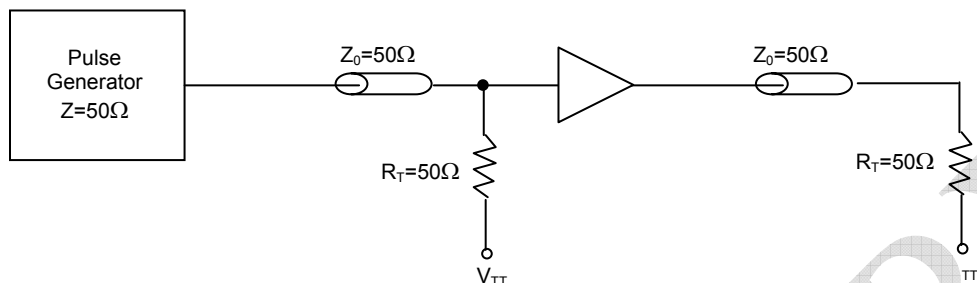


Figure 9. CCLK ASM2I99448 AC Test Reference for $V_{CC} = 3.3V$ and V_{CC}

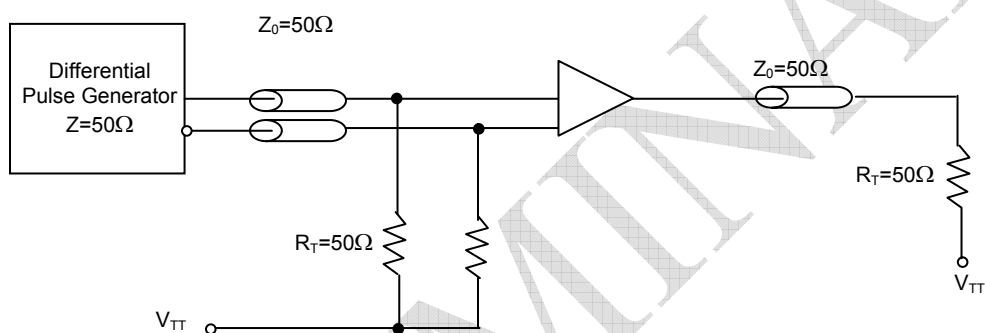
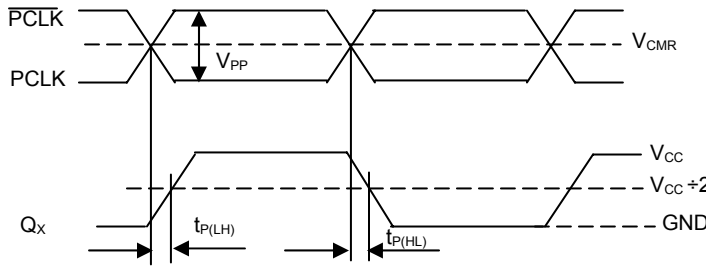
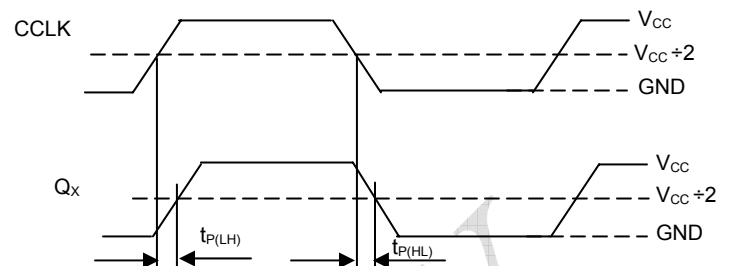
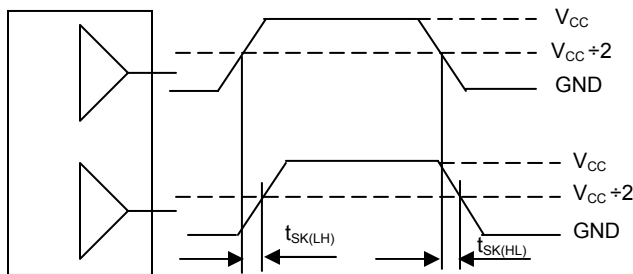


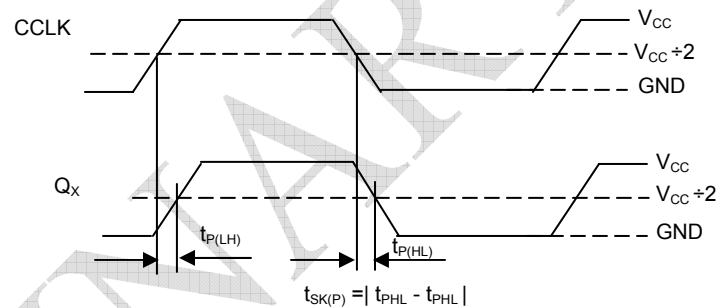
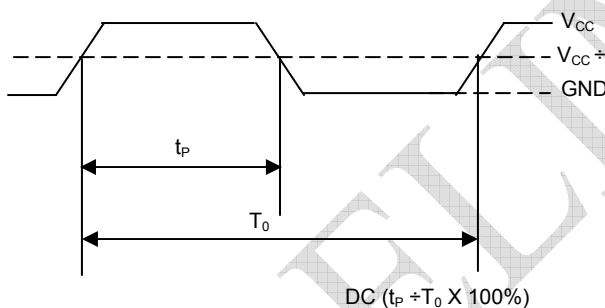
Figure 10. PCLK ASM2I99448 AC Test Reference



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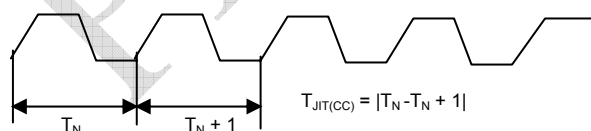
Figure 11. Propagation Delay (t_{PD}) Test ReferenceFigure 12. Propagation Delay (t_{PD}) Test Reference

The pin-to-pin skew is defined as the worst case difference in propagation between any similar delay path within a single device

Figure 13. Output-to-Output Skew $t_{SK(LH, HL)}$ Figure 14. Output Pulse Skew ($t_{SK(P)}$) Test Reference

The time from the output controlled edge to the non-controlled edge, divided by the time output controlled edge, expressed as a percentage.

Figure 15. Output Duty Cycle (DC)



The variation in cycle time of a single between adjacent cycles, over a random sample of adjacent cycle pairs

Figure 17. Cycle-to-Cycle Jitter Reference

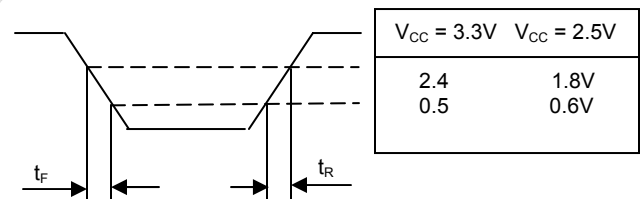
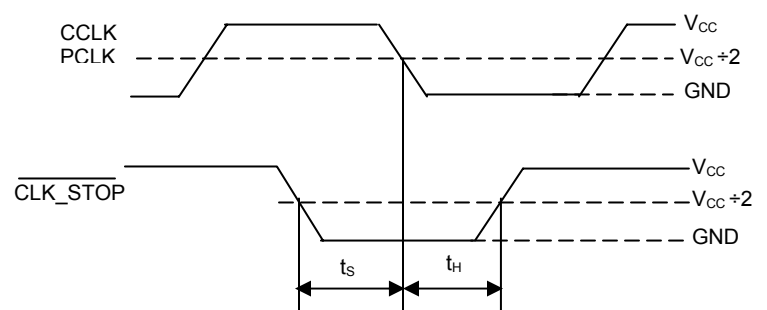


Figure 16. Output Transition Time Test Reference

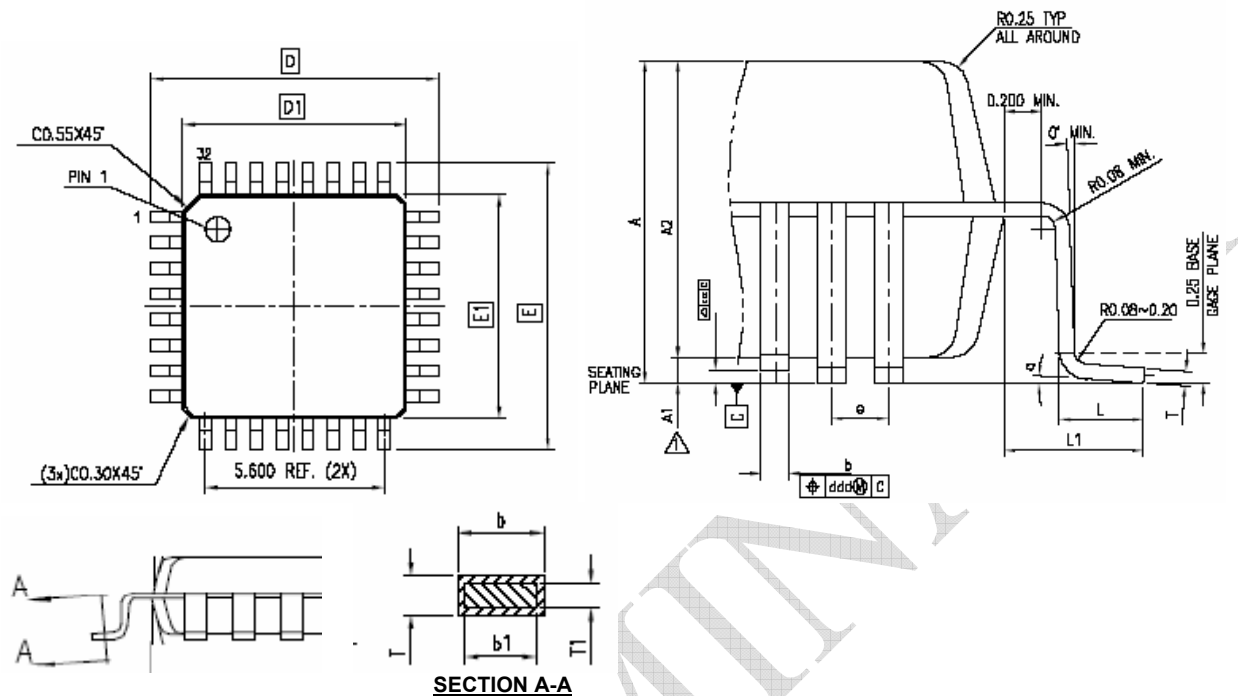
Figure 18. Setup and Hold Time (t_S, t_H) Test



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Package Information

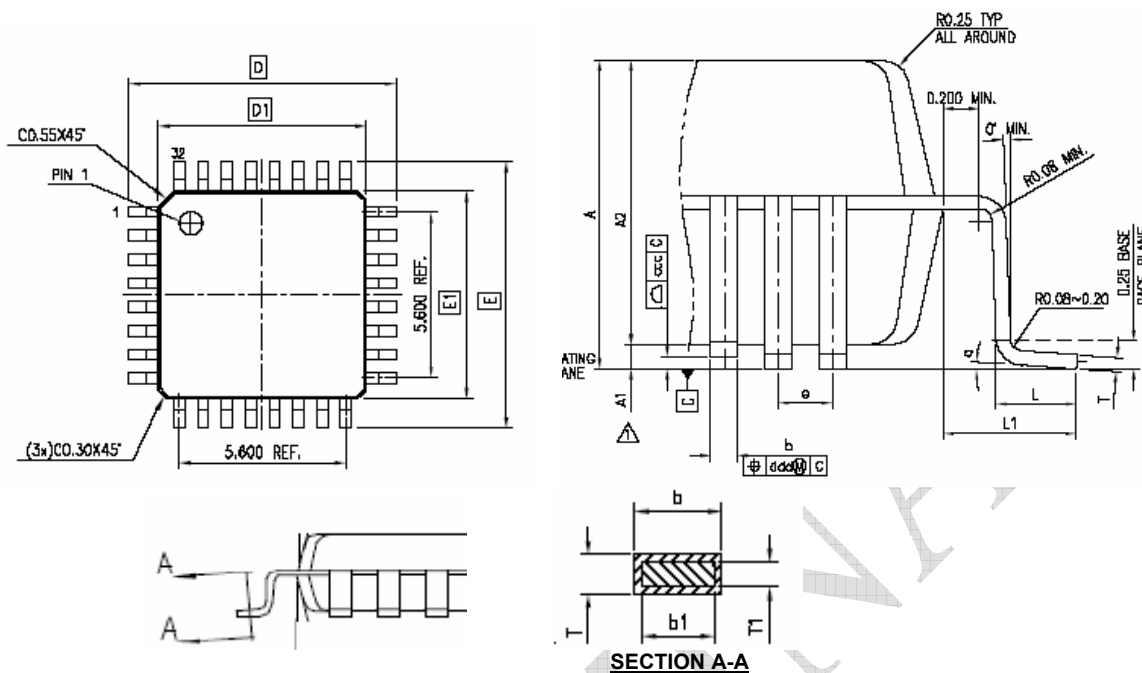
32-lead TQFP Package



Symbol	Dimensions			
	Inches		Millimeters	
	Min	Max	Min	Max
A	...	0.0472	...	1.2
A1	0.0020	0.0059	0.05	0.15
A2	0.0374	0.0413	0.95	1.05
D	0.3465	0.3622	8.8	9.2
D1	0.2717	0.2795	6.9	7.1
E	0.3465	0.3622	8.8	9.2
E1	0.2717	0.2795	6.9	7.1
L	0.0177	0.0295	0.45	0.75
L1	0.03937 REF		1.00 REF	
T	0.0035	0.0079	0.09	0.2
T1	0.0038	0.0062	0.097	0.157
b	0.0118	0.0177	0.30	0.45
b1	0.0118	0.0157	0.30	0.40
R0	0.0031	0.0079	0.08	0.2
a	0°	7°	0°	7°
e	0.031 BASE		0.8 BASE	



32-lead LQFP Package



Symbol	Dimensions			
	Inches		Millimeters	
	Min	Max	Min	Max
A		0.0630	...	1.6
A1	0.0020	0.0059	0.05	0.15
A2	0.0531	0.0571	1.35	1.45
D	0.3465	0.3622	8.8	9.2
D1	0.2717	0.2795	6.9	7.1
E	0.3465	0.3622	8.8	9.2
E1	0.2717	0.2795	6.9	7.1
L	0.0177	0.0295	0.45	0.75
L1	0.03937 REF		1.00 REF	
T	0.0035	0.0079	0.09	0.2
T1	0.0038	0.0062	0.097	0.157
b	0.0118	0.0177	0.30	0.45
b1	0.0118	0.0157	0.30	0.40
R0	0.0031	0.0079	0.08	0.20
e	0.031 BASE		0.8 BASE	
a	0°	7°	0°	7°



rev 0.3

Ordering Information

Part Number	Marking	Package Type	Operating Range
ASM2I99448-32-LT	ASM2I99448L	32-pin LQFP, Tray	Industrial
ASM2I99448-32-LR	ASM2I99448L	32-pin LQFP –Tape and Reel	Industrial
ASM2I99448G-32-LT	ASM2I99448GL	32-pin LQFP, Tray, Green	Industrial
ASM2I99448G-32-LR	ASM2I99448GL	32-pin LQFP –Tape and Reel, Green	Industrial
ASM2I99448-32-ET	ASM2I99448E	32-pin TQFP, Tray	Industrial
ASM2I99448-32-ER	ASM2I99448E	32-pin TQFP –Tape and Reel	Industrial
ASM2I99448G-32-ET	ASM2I99448GE	32-pin TQFP, Tray, Green	Industrial
ASM2I99448G-32-ER	ASM2I99448GE	32-pin TQFP –Tape and Reel, Green	Industrial

Device Ordering Information

A S M 2 I 9 9 4 4 8 G - 3 2 - L R

R = Tape & reel, T = Tube or Tray

O = SOT	U = MSOP
S = SOIC	E = TQFP
T = TSSOP	L = LQFP
A = SSOP	U = MSOP
V = TVSOP	P = PDIP
B = BGA	D = QSOP
Q = QFN	X = SC-70

DEVICE PIN COUNT

F = LEAD FREE AND RoHS COMPLIANT PART
G = GREEN PACKAGE

PART NUMBER

X = Automotive (-40C to +125C)	I = Industrial (-40C to +85C)	P or n/c = Commercial (0C to +70C)
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1 = Reserved	6 = Power Management
2 = Non PLL based	7 = Power Management
3 = EMI Reduction	8 = Power Management
4 = DDR support products	9 = Hi Performance
5 = STD Zero Delay Buffer	0 = Reserved

ALLIANCE SEMICONDUCTOR MIXED SIGNAL PRODUCT



Alliance Semiconductor Corporation
2575, Augustine Drive,
Santa Clara, CA 95054
Tel# 408-855-4900
Fax: 408-855-4999
www.alisc.com

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Note: This product utilizes US Patent # 6,646,463 Impedance Emulator Patent issued to Alliance Semiconductor, dated 11-11-2003

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